

HEAT-DISPERSING MODULE OF ELECTRONIC DEVICE

ABSTRACT OF THE DISCLOSURE

A heat-dispersing module of an electronic device is disclosed. The heat-dispersing module includes: a housing having a top surface, a bottom surface, a first side surface and a second side surface, wherein the first side surface is opposite to the second side surface; a heat-dispersing fan mounted on the first side surface of the housing; a first vent area disposed on the second side surface of the housing; a second vent area disposed on the top surface of the housing; and a printed circuit board positioned in the housing, thereby a first airflow channel is formed between the top surface of the housing and the printed circuit board and a second airflow channel is formed between the bottom surface of the housing and the printed circuit board, wherein the printed circuit board produces a relatively higher heat at the second airflow channel than the first airflow channel and a distance of the second airflow channel from the printed circuit board to the bottom surface is relatively larger than that of the first airflow channel from the printed circuit board to the top surface.